

Patent

Case No: 55259US005

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

First Named Inventor: OKADA, MITSUHIKO

Application No.: 09/719,893

Group Art Unit: 1711

Filed: December 19, 2000

Examiner: Melanie D. Bissett

Title: HEAT CONDUCTIVE SHEET AND METHOD OF PRODUCING THE SHEET

AMENDMENT WITH REQUEST FOR CONTINUED EXAMINATION
UNDER 37 C.F.R. § 1.114Commissioner for Patents
Washington, DC 20231CERTIFICATE OF TRANSMISSION

To Fax No.: 703-872-9311

I hereby certify that this correspondence is being facsimile transmitted to the U.S. Patent and Trademark Office on:

22-NOV-02

Date

Dean M. Harts

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Dear Sir:

The following amendment and remarks are submitted in response to the Final Office Action dated August 22, 2002 as well as the Advisory Action dated November 1, 2002. Entry of the enclosed amendment and reconsideration of the application is requested.

In the Specification

On page 14, please replace the following paragraph starting on line 16 and ending on line 23:

When the biaxially oriented polyester film is used as the support to laminate the substrate on the support and when the high density polyethylene film is used as the substrate, a re-peelable acrylic adhesive having high bonding power to the polyester film can be used appropriately as the adhesive for bonding the support and the substrate. When it is desired to obtain a heat conductive sheet having high bonding power as the final product, it is preferred to use a release film subjected to the release treatment (preferably, silicone treatment) for the support and an adhesive having particularly high bonding power as the adhesive.

DMH